Activation of P-Type Layers of Tunnel Junctions in Micro-LEDs
Tech ID: 32270 / UC Case 2021-551-0

BACKGROUND
P-type gallium nitride (p-GaN) is difficult to contact electrically and has a low hole concentration and mobility in conventional commercial III-nitride LEDs. This means that p-GaN cannot be used as a current spreading layer and that traditional p-contacts will add significant voltage to devices. Despite these inherent problems, all commercial light emitting devices utilize traditional p-contacts and materials other than p-GaN for current spreading, which typically involves a high barrier for tunneling. Unfortunately, current approaches to reduce the tunneling barrier are associated with losses, either in terms of voltage or resistance increases, or optical losses in the final device performance. These penalties exist even in smaller LED devices such as mini-LEDs and micro-LEDs.

DESCRIPTION
Researchers at the University of California, Santa Barbara have fabricated low forward voltage micro-LEDs with an epitaxial tunnel junction comprised of p+GaN, an InAlGaN insertion layer, and n+GaN layers grown using metalorganic chemical vapor deposition (MOCVD). The InAlGaN insertion layer offers a smaller energy bandgap than the GaN layers, which works to reduce the depletion width of the tunnel junctions and increase the tunnel probability. Tunnel junction micro-LEDs with an n-type and p-type InAlGaN insertion layer demonstrated a very stable low forward voltage at 20A cm⁻². Therefore, fabrication of micro-LEDs with low forward voltage is achieved, increasing the potential for next-generation display applications.

ADVANTAGES
▶ Low forward voltage
▶ Reduced tunnel junction depletion width
▶ Increased tunnel probability

APPLICATIONS
▶ Micro-LEDs

PATENT STATUS
Patent Pending

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS
▶ Method for Improved Surface of (Ga,Al,In,B)N Films on Nonpolar or Semipolar Substrates
▶ High Efficiency LED with Optimized Photonic Crystal Extractor
▶ Enhanced Optical Polarization of Nitride LEDs by Increased Indium Incorporation
▶ Lateral Growth Method for Defect Reduction of Semipolar Nitride Films
▶ Vertical Cavity Surface-Emitting Lasers with Continuous Wave Operation
▶ Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-183)
▶ Internal Heating for Ammonothermal Growth of Group-III Nitride Crystals
▶ Defect Reduction in GaN films using in-situ SiNx Nanomask
▶ Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
▶ Highly Efficient Blue-Violet III-Nitride Semipolar Laser Diodes
▶ Hybrid Growth Method for Improved III-Nitride Tunnel Junction Devices
▶ Phosphor-Free White Light Source
- Low Temperature Deposition of Magnesium Doped Nitride Films
- Transparent Mirrorless (TML) LEDs
- Improved GaN Substrates Prepared with Ammonothermal Growth
- Laser Diode With Tunnel Junction Contact Surface Grating
- Optimization of Laser Bar Orientation for Nonpolar Laser Diodes
- High Efficiency Semipolar AlGaN-Cladding-Free Laser Diodes
- Size-Independent Forward Voltage Micro-LED with an Epitaxial Junction
- Method for Enhancing Growth of Semipolar Nitride Devices
- III-Nitride Tunnel Junction with Modified Interface
- Growth of Polyhedron-Shaped Gallium Nitride Bulk Crystals
- Nonpolar III-Nitride LEDs With Long Wavelength Emission
- Improved Fabrication of Nonpolar InGaN Thin Films, Heterostructures, and Devices
- Growth of High-Quality, Thick, Non-Polar M-Plane GaN Films
- Increased Light Extraction with Multistep Deposition of ZnO on GaN
- Method for Manufacturing Improved III-Nitride LEDs and Laser Diodes: Monolithic Integration of Optically Pumped and Electrically Injected III-Nitride LEDs
- Selective-Area Mesoporous Semiconductors And Devices For Optoelectronic And Photonic Applications
- High-Efficiency, Mirrorless Non-Polar and Semi-Polar Light Emitting Devices
- Method for Growing High-Quality Group III-Nitride Crystals
- Controlled Photoelectrochemical (PEC) Etching by Modification of Local Electrochemical Potential of Semiconductor Structure
- Incorporating Temperature-Sensitive Layers in III-N Devices
- Oxynitride Phosphors for Use in White Light LEDs
- Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
- (In,Ga,Al)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
- MOCVD Growth of Planar Non-Polar M-Plane Gallium Nitride
- Reduced Dislocation Density of Non-Polar GaN Grown by Hydride Vapor Phase Epitaxy
- Heterogeneously Integrated GaN on Si Photonic Integrated Circuits
- Reduction in Leakage Current and Increase in Efficiency of III-Nitride MicroLEDs
- Methods for Fabricating III-Nitride Tunnel Junction Devices
- Low-Droop LED Structure on GaN Semi-polar Substrates
- Contact Architectures for Tunnel Junction Devices
- GaN Interlayer Design to Fully Eliminate V-Pits from InGaN Pseudo-Substrates
- Semi-polar LED/LD Devices on Relaxed Template with Misfit Dislocation at Hetero-interface
- Photoelectrochemical Etching Of P-Type Semiconductor Heterostructures
- Semipolar-Based Yellow, Green, Blue LEDs with Improved Performance
- Growth of Semipolar III-V Nitride Films with Lower Defect Density
- III-Nitride Tunnel Junction LED with High Wall Plug Efficiency
- Improved Manufacturing of Solid State Lasers via Patternning of Photonic Crystals
- Solid Solution Phosphors for Use in Solid State White Lighting Applications
- Multifaceted III-Nitride Surface-Emitting Laser
- Tunable White Light Based on Polarization-Sensitive LEDs
- Cleaved Facet Edge-Emitting Laser Diodes Grown on Semipolar GaN
- Growth of High-Performance M-plane GaN Optical Devices
- Packaging Technique for the Fabrication of Polarized Light Emitting Diodes
- Improved Anisotropic Strain Control in Semipolar Nitride Devices
- High Light Extraction Efficiency III-Nitride LED
- III-V Nitride Device Structures on Patterned Substrates
- Hexagonal Wurtzite Type Epitaxial Layer with a Low Alkali-Metal Concentration
- Method for Increasing GaN Substrate Area in Nitride Devices
- Nitride Based Ultraviolet LED with an Ultraviolet Transparent Contact
- Growth of Planar, Non-Polar, A-Plane GaN by Hydride Vapor Phase Epitaxy
- Single or Multi-Color High Efficiency LED by Growth Over a Patterned Substrate
- GaN-Based Thermoelectric Device for Micro-Power Generation
- Limiting Strain-Relaxation in III-Nitride Heterostructures by Substrate Patternning
- Improved Manufacturing of Semiconductor Lasers
- LED Device Structures with Minimized Light Re-Absorption
- Growth of Planar Semi-Polar Gallium Nitride
- Nonpolar (Al, B, In, Ga)N Quantum Well Design
- UV Optoelectronic Devices Based on Nonpolar and Semi-polar AlInN and AlInGaN Alloys
- Defect Reduction of Non-Polar and Semi-Polar III-Nitrides
- III-Nitride Based VCSEL with Curved Mirror on P-Side of the Aperture
- Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-150)
- Suppression of Defect Formation and Increase in Critical Thickness by Silicon Doping
- Wafer Bonding for Embedding Active Regions with Relaxed Nanostructures
- Enhancing Growth of Semipolar (Al,In,Ga,B)N Films via MOCVD